

Description

The HSS2307 is the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

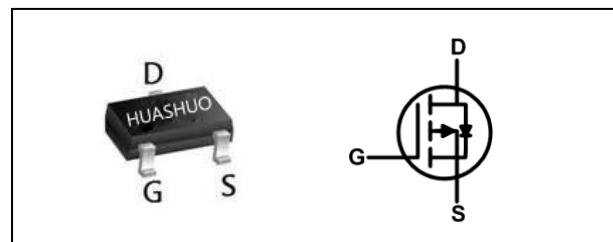
The HSS2307 meet the RoHS and Green Product requirement with full function reliability approved.

Product Summary

V _{DS}	-20	V
R _{DS(ON),typ}	20	mΩ
I _D	-6	A

- Super Low Gate Charge
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

SOT 23 Pin Configurations



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	-20	V
V _{GS}	Gate-Source Voltage	±12	V
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ -4.5V ₁	-6	A
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ -4.5V ₁	-4	A
I _{DM}	Pulsed Drain Current ²	-24	A
P _D @T _A =25°C	Total Power Dissipation ³	1.4	W
P _D @T _A =70°C	Total Power Dissipation ³	0.9	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	125	°C/W
R _{θJA}	Thermal Resistance Junction-Ambient ¹ (t ≤ 10s)	---	90	°C/W

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250μA	-20	---	---	V
△BV _{DSS} /△T _J	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =-1mA	---	-0.014	---	V/°C
R _{DSON}	Static Drain-Source On-Resistance ₂	V _{GS} =-4.5V , I _D =-6A	---	20	25	mΩ
		V _{GS} =-2.5V , I _D =-5A	---	25	30	
		V _{GS} =-1.8V , I _D =-3A	---	38	45	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250μA	-0.5	-0.7	-1.0	V
△V _{GS(th)}	V _{GS(th)} Temperature Coefficient		---	3.95	---	mV/°C
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-16V , V _{GS} =0V , T _J =25°C	---	---	-1	uA
		V _{DS} =-16V , V _{GS} =0V , T _J =55°C	---	---	-5	
I _{GS}	Gate-Source Leakage Current	V _{GS} =±12V , V _{DS} =0V	---	---	±100	nA
g _{fs}	Forward Transconductance	V _{DS} =-5V , I _D =-6A	---	8	---	S
Q _g	Total Gate Charge (-4.5V)	V _{DS} =-10V , V _{GS} =-4.5V , I _D =-6A	---	17	---	nC
Q _{gs}	Gate-Source Charge		---	4.3	---	
Q _{gd}	Gate-Drain Charge		---	4.3	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =-10V , V _{GS} =-4.5V , R _G =3.3Ω, I _D =-3A	---	23	---	ns
T _r	Rise Time		---	31	---	
T _{d(off)}	Turn-Off Delay Time		---	70	---	
T _f	Fall Time		---	50	---	
C _{iss}	Input Capacitance	V _{DS} =-10V , V _{GS} =0V , f=1MHz	---	2100	---	pF
C _{oss}	Output Capacitance		---	489	---	
C _{rss}	Reverse Transfer Capacitance		---	304	---	

Diode Characteristics

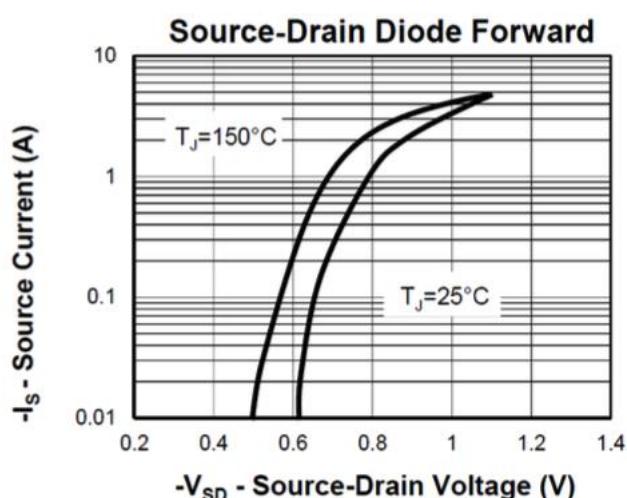
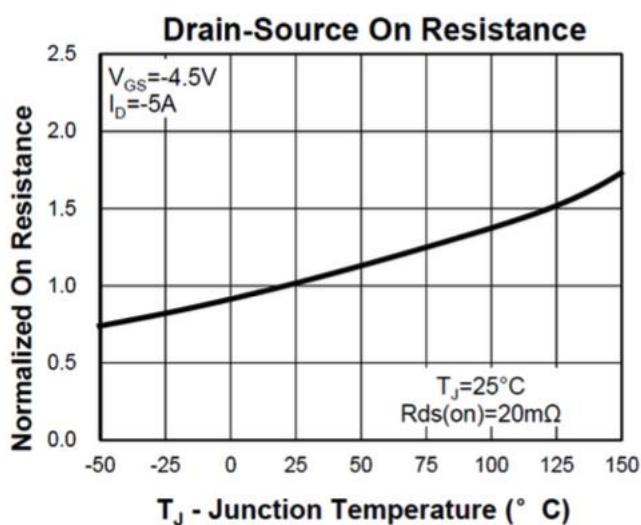
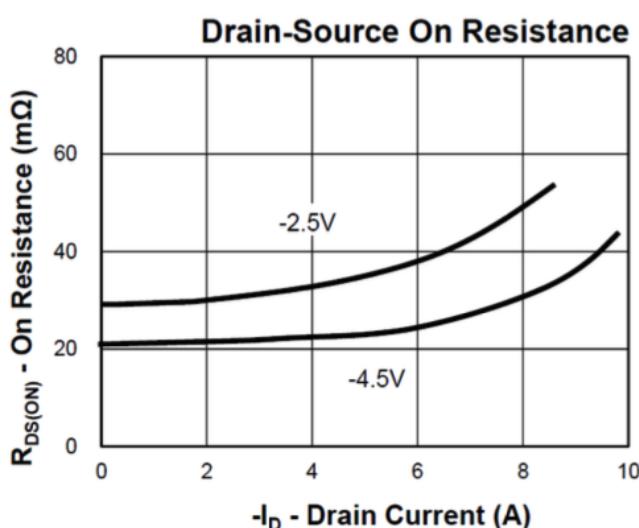
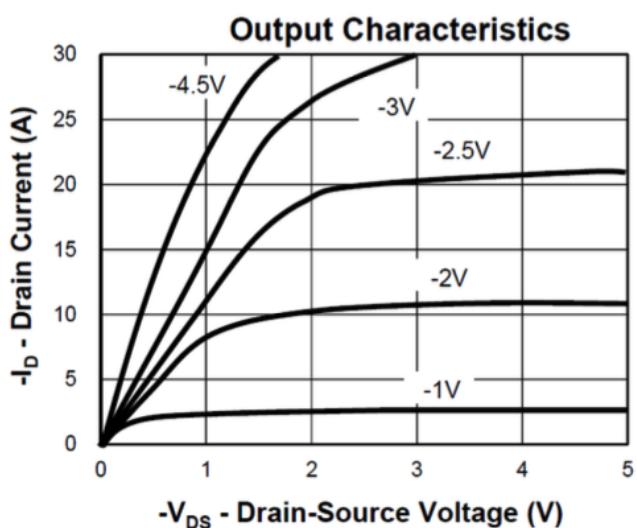
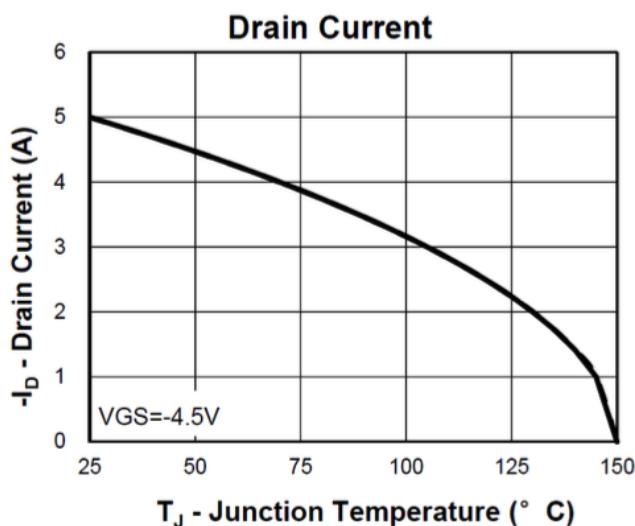
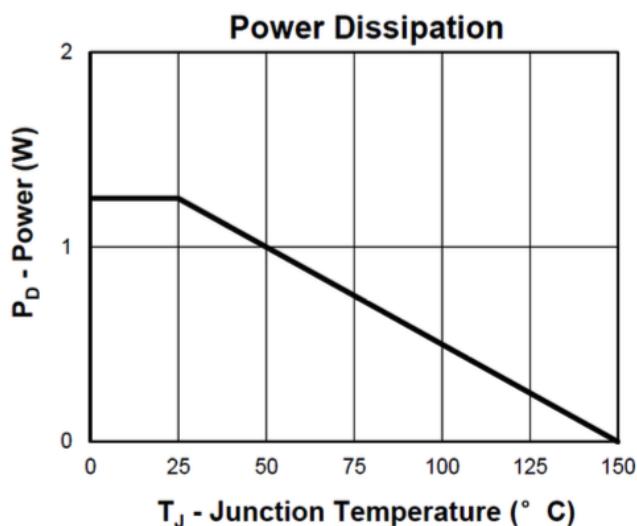
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _s	Continuous Source Current _{1,4}	V _G =V _D =0V , Force Current	---	---	-6	A
I _{SM}	Pulsed Source Current _{2,4}		---	---	-24	A
V _{SD}	Diode Forward Voltage ₂	V _{GS} =0V , I _s =-1A , T _J =25°C	---	---	-1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The power dissipation is limited by 150°C junction temperature
- 4.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



Typical Characteristics



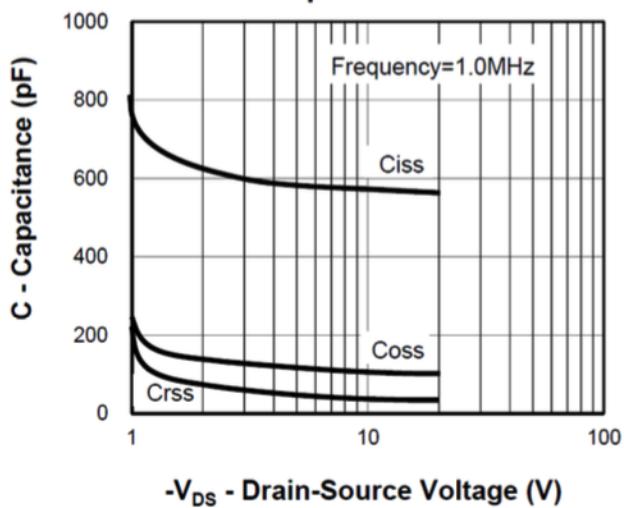


HUASHUO
SEMICONDUCTOR

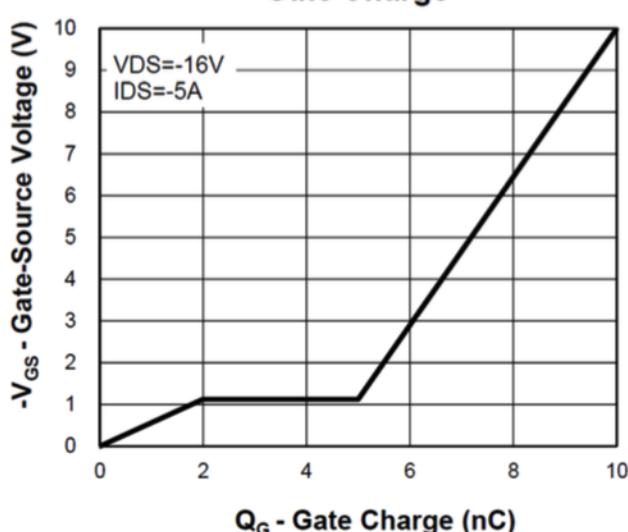
HSS2307

P-Ch 20V Fast Switching MOSFETs

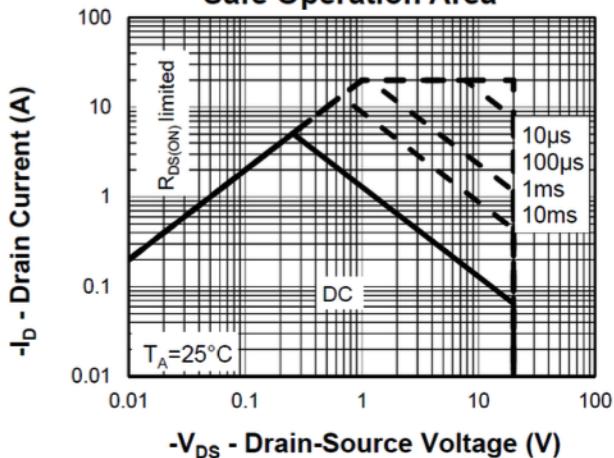
Capacitance



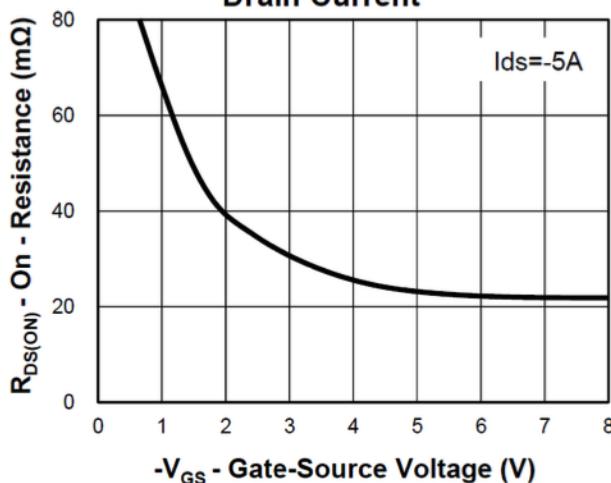
Gate Charge



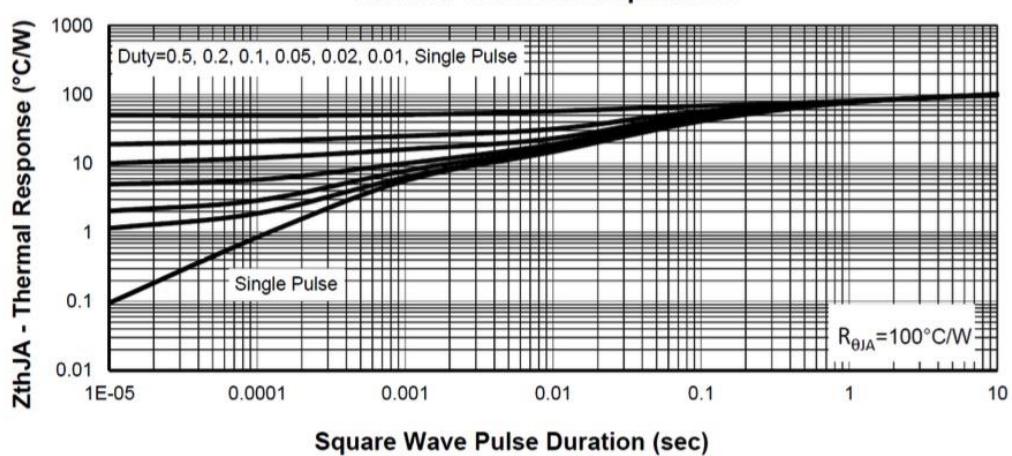
Safe Operation Area



Drain Current



Thermal Transient Impedance



Ordering Information

Part Number	Package code	Packaging
HSS2307	SOT-23L	3000/Tape&Reel

